

BERGQUIST GAP PAD TGP HC5000,GAP PAD HC 5.0

产品名称	BERGQUIST GAP PAD TGP HC5000,GAP PAD HC 5.0
公司名称	深圳市华思瑞科技有限公司
价格	10.00/PCS
规格参数	品牌:BERGQUIST 型号:GAP PAD HC 产地:USA
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产品详情

BERGQUIST GAP PAD TGP HC5000,Formerly known as GAP PAD HC 5.0

Highly Conformable, Thermally Conductive, Low-Modulus Material

Features and Benefits

Thermal conductivity: 5.0 W/m-K

High-compliance, low compression stress

Fiberglass reinforced for shear and

tear resistance

BERGQUIST GAP PAD TGP HC5000 is a soft and compliant gap filling material with a thermal conductivity of 5.0 W/m-K. The material offers exceptional thermal performance at low pressures due to a unique filler package and low-modulus resin formulation. The enhanced material is ideal for applications requiring low stress on components and boards during assembly.

BERGQUIST GAP PAD TGP HC5000 maintains a conformable nature that allows for excellent interfacing and wet-out characteristics, even to surfaces with high roughness and/or topography.

BERGQUIST GAP PAD TGP HC5000 is offered with natural inherent tack on both sides of the material,

eliminating the need for thermally-impeding adhesive layers.

The top side has minimal tack for ease of handling. BERGQUIST GAP PAD TGP HC5000 is supplied with protective liners on both sides.

BERGQUIST GPHC5.0 Typical Applications Include:

Telecommunications

ASICs and DSPs

Consumer electronics

Thermal modules to heat sinks

Configurations Available:

Sheet form and die-cut parts